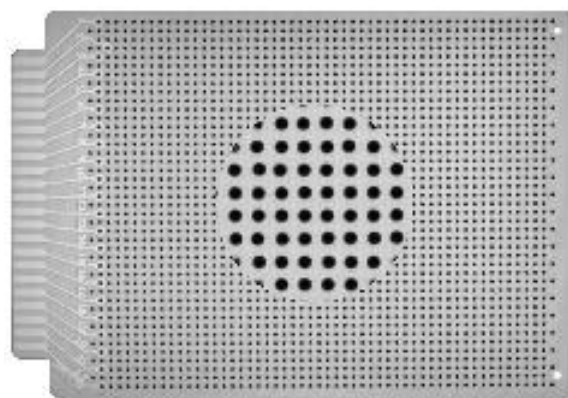




3662

4.5" x 6.5"

Circuit Pattern:
Contacts:

Contacts Only
22/44 @ .156 Ctrs,
Ni/Gold

Width/Thick:
Height:

6.50"/.062"
4.50"

16-Pin DIP Capacity:

50

Material:

CEM-1.

Wire-Wrap Terminals:

T44, T46, T49, T68

Wire-Wrap Socket Pins:

R32

Solder Connector:

R644

Extender:

3690

Rec. Card Cage:

Series 13

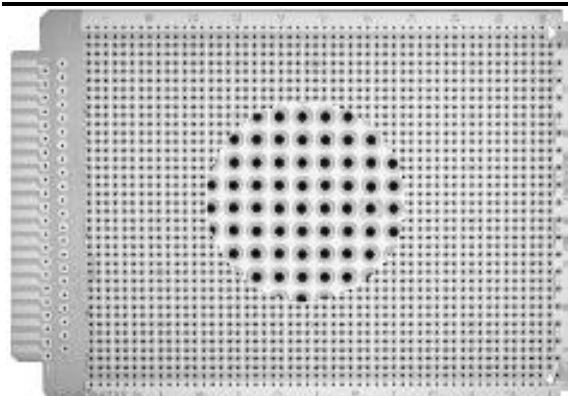
Wire-Wrap Connector:

R644-3

Hole Diameter:

.042"

- Unrestricted component placement over entire board surface
- Layout paper and instructions included
- Row and column legend provided



3662A6

4.5" x 6.5"

Circuit Pattern:
Contacts:

Ground Plane
22/44 @ .156" Ctrs,
Ni/Gold

Width/Thick:
Height:

6.50"/.062"
4.50"

16-Pin DIP Capacity:

90

Material:

CEM-1 .

Wire-Wrap Terminals:

T44, T46, T49, T68

Wire-Wrap Socket Pins:

R32

Solder Connector:

R644

Extender:

3690

Rec. Card Cage:

Series 13

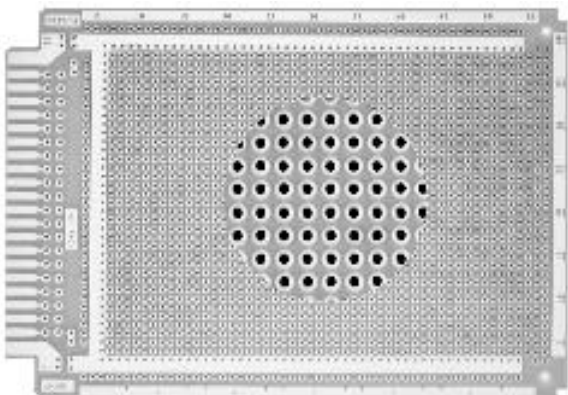
Wire-Wrap Connector:

R644-3

Hole Diameter:

.042"

- 0.085" diameter clearance area around holes
- Ground plane on component side; wiring side has contacts only
- To commit wire-wrap pins to ground planes, use Vector T124 solder washers, available separately
- Plane surface is solder-coated for user convenience
- Layout paper and instructions included
- Row and column legend provided



3662-9

4.5" x 6.5"

Circuit Pattern:
Contacts:

Pad-Per-Hole
22/44 @ .156" Ctrs,
Ni/Gold

Width/Thick:
Height:

6.50"/.062"
4.50"

16-Pin DIP Capacity:

48

Material:

FR4 Epoxy Glass

Wire-Wrap Terminals:

T44, T46, T49, T68

Wire-Wrap Socket Pins:

R32

Solder Connector:

R644

Extender:

3690

Rec. Card Cage:

Series 13

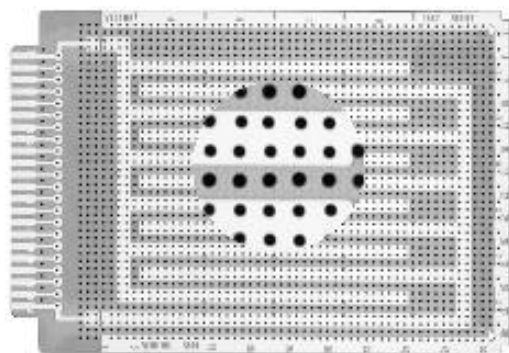
Wire-Wrap Connector:

R644-3

Hole Diameter:

.042"

- 0.080" diameter, isolated solder pad around holes, both sides
- Pad and bus surfaces solder-coated for quick, convenient soldering
- Row and column legends provided
- Layout paper and instructions included



3682-2

4.5" x 6.5"

Circuit Pattern:
Contacts:

Interleaved Buses
22/44 @ .156" Ctrs,
Ni/Gold

Width/Thick:
Height:

6.50"/.062"
4.50"

16-Pin DIP Capacity:

24

Material:

CEM-1

Wire-Wrap Terminals:

T44, T46, T49, T68

Wire-Wrap Socket Pins:

R32

Solder Connector:

R644

Extender:

3690

Rec. Card Cage:

Series 13

Wire-Wrap Connector:

R644-3

Hole Diameter:

.042"

- Bus pattern on wiring side, solder-coated for user convenience
- Bus outline traced on component side to facilitate component placement
- Mounts DIPs with 0.3", 0.4" and 0.9" lead spacing
- Unclad test point area at top of board
- Layout paper and instructions included
- Row and column legends provided

Note: Same as 3682-4 but without Ground Plane

3682-4

4.5" x 6.5"

Circuit Pattern:

Interleaved Bus/
Ground Plane
22/44 @ .156" Ctrs,
Ni/Gold

Contacts:

6.50"/.062"

Width/Thick:

Height:

4.50"

16-Pin DIP Capacity:

24

Material:

CEM-1

Wire-Wrap Terminals:

T44, T46, T49, T68

Wire-Wrap Socket Pins:

R32

Solder Connector:

R644

Extender:

3690

Rec. Card Cage:

Series 13

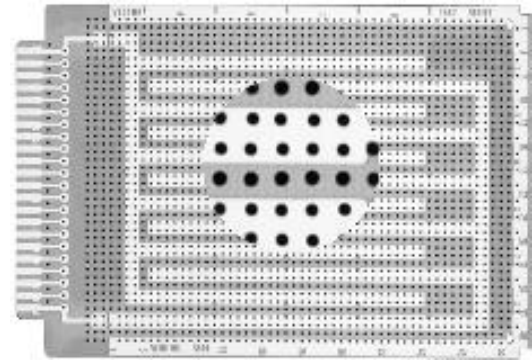
Wire-Wrap Connector:

R644-3

Hole Diameter:

.042"

- Power bus in rows across component side; overall ground plane on wiring side
- 0.085" etched clearance area around each hole on ground plane side
- Bus and plane surfaces solder coated for user convenience
- To commit wire-wrap pins to ground planes, use Vector T124 solder washers, available separately
- Layout paper and instructions included
- Row and column legends provided



3677-2

4.5" x 6.5"

Circuit Pattern:

3-Hole Solder Pad
22/44 @ .156" Ctrs.
Ni/Gold

Contacts:

6.50"/.062"

Width/Thick:

Height:

4.50"

16-Pin DIP Capacity:

12

Material:

CEM-1

Wire-Wrap Terminals:

T44, T46, T49, T68

Wire-Wrap Socket Pins:

R32

Solder Connector:

R644

Extender:

3690

Rec. Card Cage:

Series 13

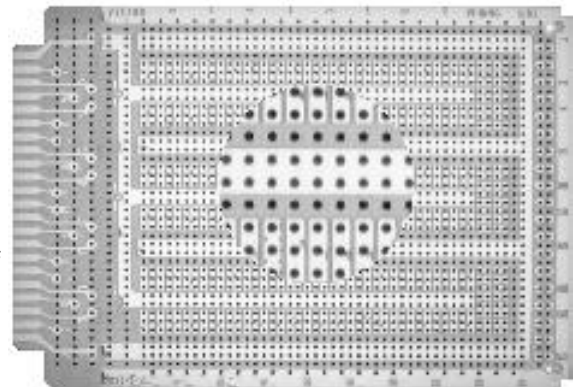
Wire-Wrap Connector:

R644-3

Hole Diameter:

.042"

- 3-hole solder pads (0.28" x 0.080") for interconnecting multiple component leads
- Voltage/ground buses interleaved between pad areas on wiring side
- Row and column legends provided
- Test point area, with solder pads around holes, provided along back edge of board
- Layout paper and instructions included



4112-4

4.5" x 6.5"

Circuit Pattern:

3-Hole Solder Pad
22/44 @ .156" Ctrs,
Ni/Gold

Contacts:

6.50"/.062"

Width/Thick:

Height:

4.50"

16-Pin DIP Capacity:

25

Material:

CEM-1

Wire-Wrap Terminals:

T44, T46, T49, T68

Wire-Wrap Socket Pins:

R32

Solder Connector:

R644

Extender:

3690

Rec. Card Cage:

Series 13

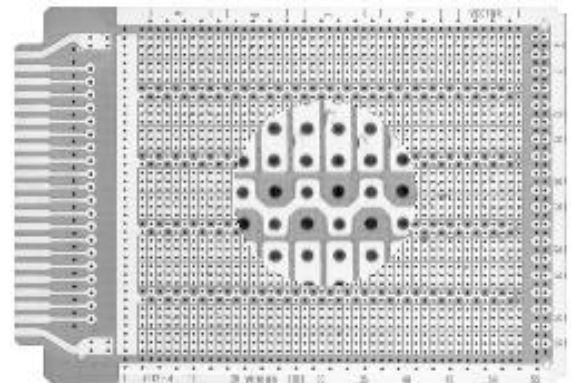
Wire-Wrap Connector:

R644-3

Hole Diameter:

.042"

- Continuous ground plane on component side with 0.085" clearance pad around each hole
- 3-hole solder pads (0.28 x 0.080") for interconnecting multiple component leads
- Row and column legends provided
- Layout paper and instructions included



3662-2

4.5" x 9.6"

Circuit Pattern:

Contacts Only
22/44 @ .156" Ctrs,
Ni/Gold

Contacts:

9.60"/.062"

Width/Thick:

Height:

4.50"

16-Pin DIP Capacity:

90

Material:

CEM-1

Wire-Wrap Terminals:

T44, T46, T49, T68

Wire-Wrap Socket Pins:

R32

Solder Connector:

R644

Extender:

3690-6

Rec. Card Cage:

Series 14

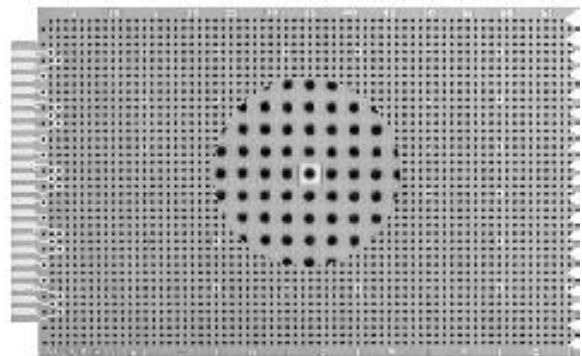
Wire-Wrap Connector:

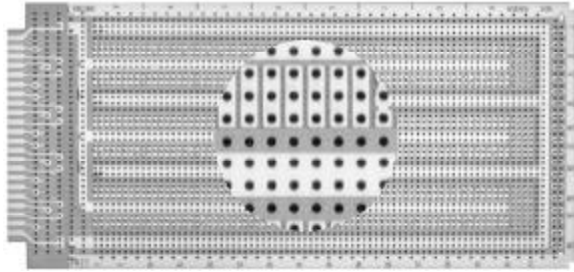
R644-3

Hole Diameter:

.042"

- Unrestricted component placement over entire board surface
- Row and column legends provided
- Layout paper and instructions included





3677

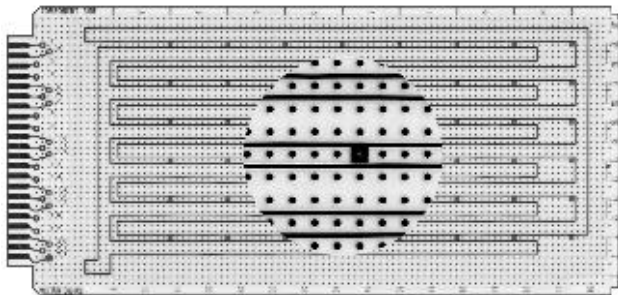
Circuit Pattern:
Contacts:

Width/Thick:
Height:
16-Pin DIP Capacity:
Material:
Wire-Wrap Terminals:
Wire-Wrap Socket Pins:
Solder Connector:
Extender:
Rec. Card Cage:
Wire-Wrap Connector:
Hole Diameter:

4.5" x 9.6"

3-Hole Solder Pad
22/44 @ .156" Ctrs.,
Ni/Gold
9.60"/.062"
4.50"
21
CEM-1
T44, T46, T49, T68
R32
R644
3690
Series 14
R644-3
.042"

- 3-hole solder pads (0.28" x 0.080") for interconnecting multiple component leads
- Row and column legends provided
- Layout paper and instructions included



3682

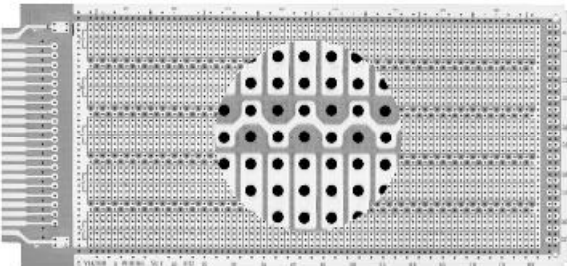
Circuit Pattern:
Contacts:

Width/Thick:
Height:
16-Pin DIP Capacity:
Material:
Wire-Wrap Terminals:
Wire-Wrap Socket Pins:
Solder Connector:
Extender:
Rec. Card Cage:
Wire-Wrap Connector:
Hole Diameter:

4.5" x 9.6"

Interleaved Buses
22/44 @ .156 Ctrs.,
Ni/Gold
9.60"/.062"
4.50"
48
CEM-1
T44, T46, T49, T68
R32
R644
3690-6
Series 13
R644-3
.042"

- Etched bus pattern on wiring side, solder-coated for user convenience
- Bus outlines traced on component side
- Mounts DIPs with 0.3", 0.4" and 0.9" lead spacings
- Layout paper and instructions included
- Row and column legends provided



4112

Circuit Pattern:
Contacts:

Width/Thick:
Height:
16-Pin DIP Capacity:
Material:
Wire-Wrap Terminals:
Wire-Wrap Socket Pins:
Solder Connector:
Extender:
Rec. Card Cage:
Wire-Wrap Connector:
Hole Diameter:

4.5" x 9.6"

3-Hole Solder Pad
22/44 @ .156" Ctrs.,
Ni/Gold
9.60"/.062"
4.50"
40
FR4 Epoxy Glass
T44, T46, T49, T68
R32
R644
3690-6
Series 13
R644-3
.042"

- Zig-zag bus pattern on wiring side provides access to voltage or ground at alternating hole positions
- 3-hole solder pads (0.28" x 0.080") for interconnecting multiple component leads
- Continuous ground plane on component side with 0.085" etched clearance area around each hole
- Layout paper and instructions included
- Row and column legends provided

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru

moschip.ru_4

moschip.ru_6

moschip.ru_9